Hans Christian Lundberg

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PROFILE

Passionate and result-oriented engineer holding an MSc in Autonomous Systems from DTU. Specialized in the full stack from *bare-metal* firmware to cloud infrastructure. I have deep experience with embedded Linux (Yocto), real-time systems, and sensor integration. With a strong toolkit in C++ and Python, I have delivered innovative solutions at FoodOp.io, Tinyfarms, and 3Shape. Ready to solve complex technical challenges at the intersection of hardware and software.

WORK EXPERIENCE

FoodOp, Copenhagen, Denmark

- Embedded Software Engineer — Sep 2024 – Present
  - Leading firmware development within automated food waste reduction.
  - Architecting real-time sensor integration and edge-processing pipelines, transforming raw data into actionable insights on resource-constrained devices.

Tinyfarms, Copenhagen, Denmark

- Firmware Engineer — Apr 2023 – Mar 2024
  - Designed a Mesh Sensor Network based on ESP32 microcontrollers (Master's Thesis).
  - Developed power-efficient C++ firmware using MQTT and Thread protocols.

3Shape, Copenhagen, Denmark

- Embedded Developer — Feb 2020 – Maj 2021
  - Developed a low-latency application streaming receiver on NVIDIA Jetson Nano.
  - Utilized Docker and Embedded Linux to bridge Windows servers and edge devices.

TECHNICAL SKILLS

CORE STACK
C, C++, Python, (Familiar with: C#, Java, MatLab)

EMBEDDED & LINUX
Embedded Linux, Yocto, Drivers, FreeRTOS, STM32, ESP32, Arduino

CLOUD, DEVOPS & DATA
Docker, Kubernetes (K8s), Git, CI/CD, PostgreSQL, Elasticsearch

ROBOTICS & SENSORS
ROS (Robot Operating System), OpenCV, Sensor Fusion, Automation

PROTOCOLS
MQTT, Thread, BLE, LoRa, ZigBee, WiFi

EDUCATION

Technical University of Denmark (DTU), Lyngby, Denmark

- MSc in Autonomous Systems — Sep 2021 – Mar 2024
  - GPA: 11.3 / 12.0
  - Thesis: Development of Mesh Sensor Modules (C++, ESP32)

Tokyo Institute of Technology, Tokyo, Japan

- MSc Electrical Engineering — Sep 2022 – Feb 2023
  - Exchange semester focusing on robotics technology and Japanese culture.

Technical University of Denmark (DTU), Lyngby, Denmark

- BEng in Electrical Engineering — Sep 2017 – Feb 2021
  - GPA: 11.0 / 12.0

New York University, New York City, NY, USA

- B.S. in Electrical Engineering — Sep 2019 – Dec 2019
  - Exchange semester